Preferred Device

General Purpose Transistors

NPN Silicon

Features

• Pb–Free Packages are Available*

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	40	Vdc
Collector – Base Voltage	V _{CBO}	60	Vdc
Emitter – Base Voltage	V _{EBO}	6.0	Vdc
Collector Current – Continuous	Ι _C	600	mAdc
Total Device Dissipation @ T _A = 25°C Derate above 25°C	P _D	625 5.0	mW mW/°C
Total Device Dissipation @ T _C = 25°C Derate above 25°C	P _D	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T _J , T _{stg}	−55 to +150	°C

THERMAL CHARACTERISTICS

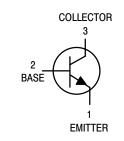
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	R_{\thetaJA}	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{\theta JC}$	83.3	°C/W

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.



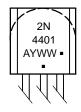
ON Semiconductor®

http://onsemi.com





MARKING DIAGRAM



2N4401 = Device Code A = Assembly Location Y = Year WW = Work Week • = Pb-Free Package

(Note: Microdot may be in either location)

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

Preferred devices are recommended choices for future use

and best overall value.

*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

Manual, SOLDERRM/D.

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

	Symbol	Min	Max	Unit	
OFF CHARACTERIS	STICS				1
Collector–Emitter B $(I_C = 1.0 \text{ mAdc}, I_E)$	V _{(BR)CEO}	40	-	Vdc	
Collector–Base Bre $(I_C = 0.1 \text{ mAdc}, I_E)$	V _{(BR)CBO}	60	-	Vdc	
Emitter-Base Breal (I _E = 0.1 mAdc, I _C	Base Breakdown Voltage V _{(BR)EBO} V _{(BR)EBO}		6.0	-	Vdc
Base Cutoff Current (V _{CE} = 35 Vdc, V _I	I _{BEV}	-	0.1	μAdc	
Collector Cutoff Cur (V _{CE} = 35 Vdc, V _I	I _{CEX}	I _{CEX} – 0.1 µ		μAdc	
ON CHARACTERIS	TICS (Note 1)				•
$ \begin{array}{l} \text{DC Current Gain} \\ (I_{C} = 0.1 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 1.0 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 10 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 150 \text{ mAdc}, V_{CE} = 1.0 \text{ Vdc}) \\ (I_{C} = 500 \text{ mAdc}, V_{CE} = 2.0 \text{ Vdc}) \end{array} $		h _{FE}	20 40 80 100 40	- - - 300 -	_
Collector-Emitter Saturation Voltage ($I_C = 150 \text{ mAdc}$, $I_B = 15 \text{ mAdc}$) ($I_C = 500 \text{ mAdc}$, $I_B = 50 \text{ mAdc}$)		V _{CE(sat)}		0.4 0.75	Vdc
Base-Emitter Saturation Voltage ($I_C = 150 \text{ mAdc}$, $I_B = 15 \text{ mAdc}$) ($I_C = 500 \text{ mAdc}$, $I_B = 50 \text{ mAdc}$)		V _{BE(sat)}	0.75 _	0.95 1.2	Vdc
SMALL-SIGNAL CH	IARACTERISTICS				
Current-Gain - Bar	ndwidth Product ($I_C = 20$ mAdc, $V_{CE} = 10$ Vdc, f = 100 MHz)	f _T	250	-	MHz
Collector-Base Cap	vacitance ($V_{CB} = 5.0 \text{ Vdc}, I_E = 0, f = 1.0 \text{ MHz}$)	C _{cb}	-	6.5	pF
Emitter–Base Capacitance (V_{EB} = 0.5 Vdc, I_C = 0, f = 1.0 MHz)		C _{eb}	-	30	pF
Input Impedance (IC	= 1.0 mAdc, V _{CE} = 10 Vdc, f = 1.0 kHz)	h _{ie}	1.0	15	kΩ
Voltage Feedback Ratio ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{re}	0.1	8.0	X 10 ⁻⁴
Small–Signal Current Gain (I_C = 1.0 mAdc, V_{CE} = 10 Vdc, f = 1.0 kHz)		h _{fe}	40	500	-
Output Admittance ($I_C = 1.0 \text{ mAdc}$, $V_{CE} = 10 \text{ Vdc}$, $f = 1.0 \text{ kHz}$)		h _{oe}	1.0	30	μmhos
SWITCHING CHAR	ACTERISTICS				
Delay Time	(V _{CC} = 30 Vdc, V _{BE} = 2.0 Vdc,	t _d	-	15	ns
Rise Time	$I_{C} = 150 \text{ mAdc}, I_{B1} = 15 \text{ mAdc})$	t _r	-	20	ns
Storage Time	$(V_{CC} = 30 \text{ Vdc}, I_C = 150 \text{ mAdc},$	t _s	-	225	ns
Fall Time	$I_{B1} = I_{B2} = 15 \text{ mAdc}$)	t _f	_	30	ns

1. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2.0%.

ORDERING INFORMATION

Device	Package	Shipping [†]
2N4401	TO-92	5,000 Units / Box
2N4401G	TO-92 (Pb-Free)	5,000 Units / Box
2N4401RLRA	TO-92	2000 / Tape & Reel
2N4401RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
2N4401RLRM	TO-92	2000 / Ammo Pack
2N4401RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
2N4401RLRP	TO-92	2000 / Ammo Pack
2N4401RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

SWITCHING TIME EQUIVALENT TEST CIRCUITS

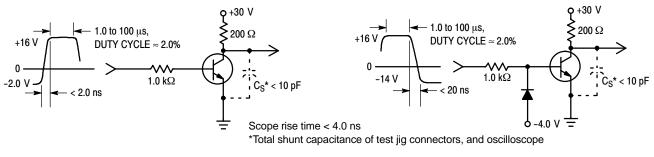
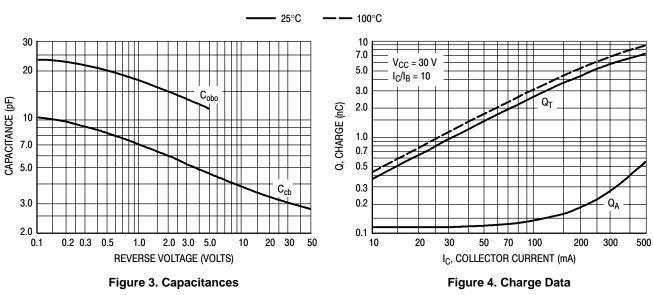
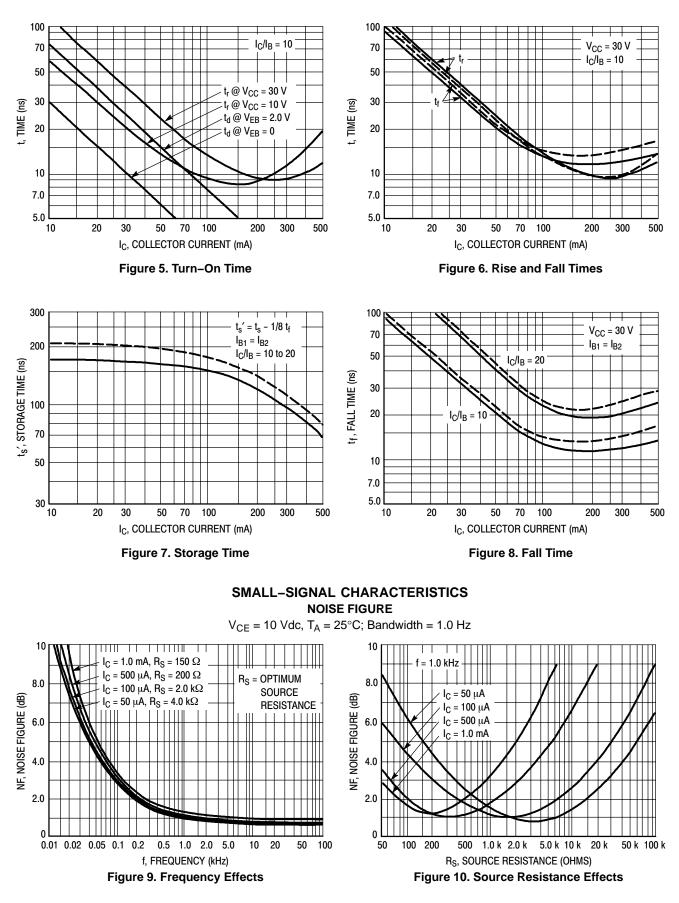


Figure 1. Turn–On Time

Figure 2. Turn–Off Time



TRANSIENT CHARACTERISTICS



h PARAMETERS

V_{CE} = 10 Vdc, f = 1.0 kHz, T_A = 25°C

This group of graphs illustrates the relationship between h_{fe} and other "h" parameters for this series of transistors. To obtain these curves, a high–gain and a low–gain unit were

selected from the 2N4401 lines, and the same units were used to develop the correspondingly numbered curves on each graph.

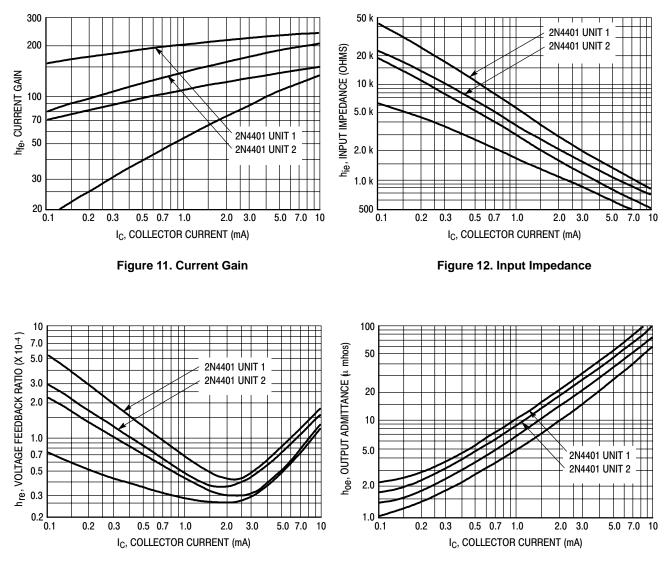
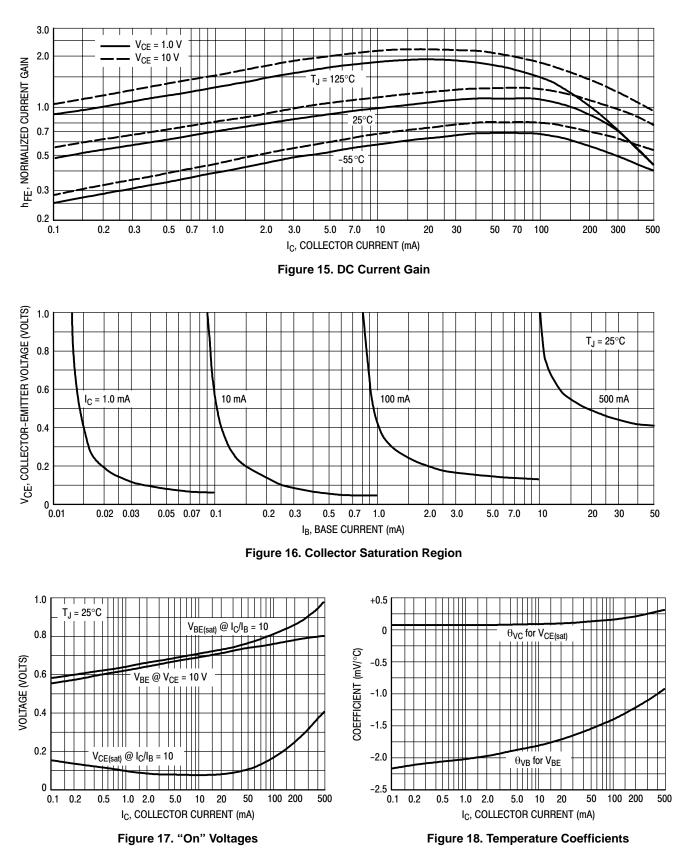


Figure 13. Voltage Feedback Ratio

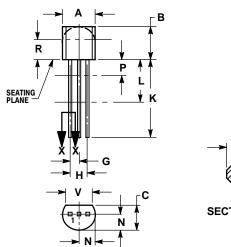
Figure 14. Output Admittance





PACKAGE DIMENSIONS

TO-92 **TO-226AA** CASE 29-11 **ISSUE AL**





NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- TIA-3M, 1982. CONTROLLING DIMENSION: INCH. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED. LEAD DIMENSION IS UNCONTROLLED IN P AND 2. 3.
- 4
- BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
ſ	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
Ν	0.080	0.105	2.04	2.66
Ρ		0.100		2.54
R	0.115		2.93	
۷	0.135		3.43	

STYLE 1: PIN 1. EMITTER

2. BASE

3. COLLECTOR

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N. American Technical Support: 800-282-9855 Toll Free USA/Canada

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ON Semiconductor Website: http://onsemi.com

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